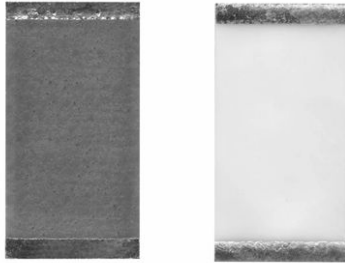


## High Stability Resistor Chips ( $< 0.25\%$ at Pn at $70\text{ }^{\circ}\text{C}$ during 1000 h) Thick Film Technology



Vishay Sfernice thick film resistor chips are specially designed to meet very stringent specifications in terms of reliability, stability  $< 0.25\%$  at Pn at  $+ 70\text{ }^{\circ}\text{C}$  during 1000 h, homogeneity, reproducibility and quality.

They conform to specifications NFC 83-240 and MIL-R-55342 D.

Evaluated to ESCC 4001/026 (see CHPHR datasheet).

Sputtered Thin Film terminations, with nickel barrier, are very convenient for high operating conditions. They can withstand thousands of very severe thermal shocks.

B (W/A), N (W/A), and F (one face) types are for solder reflow assembly.

G (W/A) and W (one face) types are for wire bonding, gluing and even high temperature solder reflow.

### FEATURES

- CHP: Standard passivated version for industrial, professional and military applications
- Robust terminations
- Large ohmic value range  $0.1\ \Omega$  to  $100\ \text{M}\Omega$
- Tight tolerance to  $0.5\%$
- HCHP: For high frequency applications
- ESCC approved see CHPHR
- High temperature ( $245\text{ }^{\circ}\text{C}$ ) see CHPHT
- SMD wraparound chip resistor
- Halogen-free according to IEC 61249-2-21 definition
- Withstand moisture resistance test of AEC-Q200
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### Note

\* This datasheet provides information about parts that are RoHS-compliant and/or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information/tables in this datasheet for details.

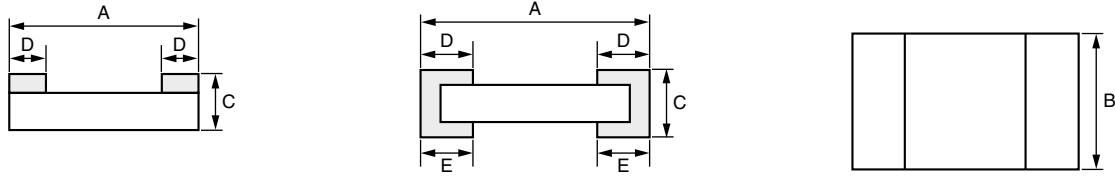
STANDARD ELECTRICAL SPECIFICATIONS								
MODEL	SIZE	RATED POWER Pn W	LIMITING ELEMENT VOLTAGE V	MAX. OVERLOAD VOLTAGE V	RESISTANCE RANGE <sup>(1)</sup> $\Omega$	TOLERANCE $\pm\%$	TEMPERATURE COEFFICIENT $\pm\text{ppm}/^{\circ}\text{C}$	UNIT WEIGHT mg
CHP0502 HCHP0502	0502	0.050	50	100	0.1 to 25M	0.5, 1, 2, 5	100, 200	1
CHP0505 HCHP0505	0505	0.125	50	100	0.1 to 10M	0.5, 1, 2, 5	100, 200	3
CHP0603 HCHP0603	0603	0.125	50	100	0.1 to 25M	0.5, 1, 2, 5	100, 200	2
CHP0805 <sup>(2)</sup> HCHP0805	0805	0.200	150	300	0.1 to 25M	0.5, 1, 2, 5	100, 200	4
CHP1005 HCHP1005	1005	0.250	150	300	0.1 to 50M	0.5, 1, 2, 5	100, 200	5
CHP1206 HCHP1206	1206	0.250	200	400	0.1 to 50M	0.5, 1, 2, 5	100, 200	8
CHP1505 HCHP1505	1505	0.500	200	400	0.1 to 75M	0.5, 1, 2, 5	100, 200	8
CHP2010 HCHP2010	2010	1.000 <sup>(3)</sup>	200	400	0.1 to 100M	0.5, 1, 2, 5	100, 200	26
CHP1020 HCHP1020	1020	1.000 <sup>(3)</sup>	200	400	0.1 to 10M	0.5, 1, 2, 5	100, 200	25
CHP2208 HCHP2208	2208	0.750	200	400	0.1 to 100M	0.5, 1, 2, 5	100, 200	21
CHP2512 CHP2512	2512	2.000 <sup>(3)</sup>	250	500	0.1 to 100M	0.5, 1, 2, 5	100, 200	42
CHP1010 CHP1010	1010	0.500	200	400	0.1 to 25M	0.5, 1, 2, 5	100, 200	12

### Notes

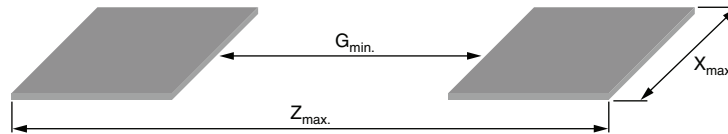
(1) Shall be read in conjunction with other tables.

(2) Model CHP0805 being same size than case 0705 with same performances, only codification of CHP0805 remains.

(3) With special assembly care.

**DIMENSIONS** in millimeters (inches)


CASE SIZE	A		B		C		D/E	
	VALUE	TOL.	VALUE	TOL.	VALUE	TOL.	VALUE	TOL.
0502	1.27 (0.050)	0.152 (0.006)	0.60 (0.024)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
0505	1.27 (0.050)	0.152 (0.006)	1.27 (0.050)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
0603	1.52 (0.060)	0.152 (0.006)	0.85 (0.033)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
0805	1.91 (0.075)	0.152 (0.006)	1.27 (0.050)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
1005	2.54 (0.100)	0.152 (0.006)	1.27 (0.050)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
1206	3.05 (0.120)	0.152 (0.006)	1.70(0.067)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
1505	3.81 (0.150)	0.152 (0.006)	1.32 (0.052)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
2010	5.08 (0.200)	0.152 (0.006)	2.54 (0.100)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
1020	2.54 (0.100)	0.152 (0.006)	5.08 (0.200)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
2208	5.58 (0.220)	0.152 (0.006)	2.00 (0.079)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
2512	6.35 (0.250)	0.152 (0.006)	3.30 (0.130)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)
1010	2.54 (0.100)	0.152 (0.006)	2.54 (0.100)	0.127 (0.005)	0.5 (0.020)	0.127 (0.005)	0.38 (0.015)	0.127 (0.005)

**SUGGESTED LAND PATTERN** (to IPC-7351A)


CASE SIZE	DIMENSION IN MM (INCHES)		
	ZMAX.	GMIN.	XMAX.
0502	1.82 (0.072)	0.10 (0.004)	0.73 (0.029)
0505	1.82 (0.072)	0.10 (0.004)	1.40 (0.055)
0603	2.37 (0.093)	0.35 (0.014)	0.98 (0.038)
0805	2.76 (0.109)	0.74 (0.029)	1.40 (0.055)
1005	3.39 (0.134)	1.37 (0.054)	1.40 (0.055)
1206	3.90 (0.154)	1.88 (0.074)	1.73 (0.068)
1505	4.66 (0.184)	2.64 (0.104)	1.45 (0.057)
2010	5.93 (0.234)	3.91 (0.154)	2.67 (0.105)
1020	3.39 (0.134)	1.37 (0.054)	5.21 (0.205)
2208	6.43 (0.253)	4.41 (0.174)	2.04 (0.080)
2512	7.20 (0.284)	5.18 (0.204)	3.19 (0.125)
1010	3.39 (0.134)	1.37 (0.054)	2.67 (0.105)



MECHANICAL SPECIFICATIONS	
Substrate	Alumina
Technology	Thick film (ruthenium oxyde)
Protection	Epoxy coating
Terminations	<p><b>B (W/A):</b> SnPb over nickel barrier for solder reflow</p> <p><b>N (W/A):</b> SnAg over nickel barrier for solder reflow</p> <p><b>F (Flip Chip):</b> SnAg over nickel barrier for solder reflow</p> <p><b>W (one face) and G (W/A) type:</b> Gold over nickel barrier for other applications</p>

**Note**

- Refer to Application Note "Guidelines for Vishay Sfernice Resistive and Inductive Components" (document number: 52029) for recommended reflow profile. Profile #3 applies.

CLIMATIC SPECIFICATIONS	
Operating temperature range	- 55 °C; + 155 °C

**Note**

- For temperature up to 215 °C please consult Vishay Sfernice

BEST TOL. AND TCR VS. OHMIC VALUE (1)		
OHMIC VALUE RANGE in $\Omega$	TIGHTEST TOLERANCE (%)	BEST TCR (ppm/°C)
$10 \Omega < R < 5M$	0.5 % (D)	100 (K)
$5 \Omega < R < 10M$	1 % (F)	100 (K)
$1 \Omega < R < R_{max}$	2 % (G)	200 (L)
$0.1 \Omega < R < R_{max}$	5 % (J)	200 (L)

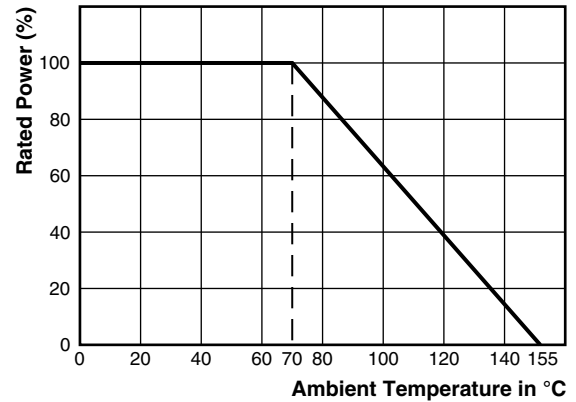
**Note**

(1) Improved performance on request

**CHIPS FOR HIGH FREQUENCY APPLICATIONS**

The HF performance of flip chip and W/A types can be improved on request. Please ask for HCHP

**POWER DERATING CURVE**



**PACKAGING**

ESD packaging available: Waffle pack and plastic tape and reel (low conductivity). Paper tapes available on request (ESD only).

SIZE	MOQ	NUMBER OF PIECES PER		TAPE WIDTH	
		WAFFLE PACK	TAPE AND MIN. MAX.		
0502	100	400	4000	8 mm	
0505		100			5000
0603					
0805		221	4000		
1005					
1206		60	2000		8 mm
1505					
2010		100	2500	8 mm	
1010					
2208		60	4000	8 mm	
1020					
2512		50	1000	8 mm	
			2000	8 mm	

**PACKAGING RULES**

**Waffle Pack**

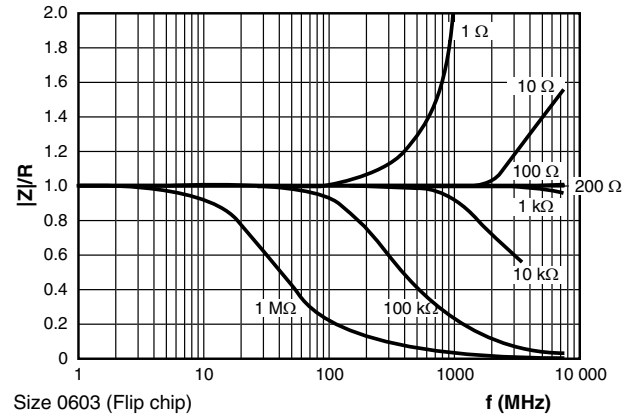
Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered exceeds maximum quantity of a single waffle pack, the waffle packs are stacked up on the top of each other and closed by one single cover.

**To get "not stacked up" waffle pack in case of ordered quantity > maximum number of pieces per package: Please consult Vishay Sfernice for specific ordering code**

**Tape and Reel**

See Part Numbering information to get the quantity desired by tape.

## TYPICAL HF PERFORMANCE OF HCHP



## POPULAR OPTIONS

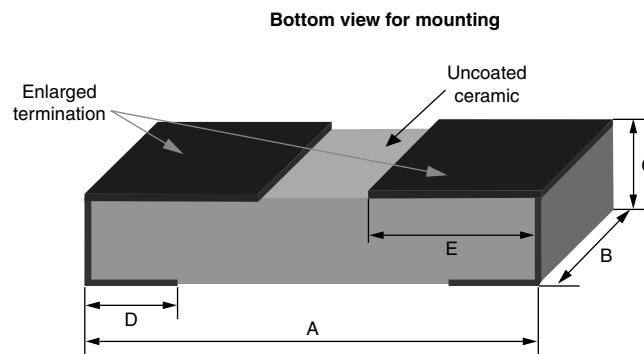
For any option it is recommended to consult Vishay Sfernice for availability first.

Option: Enlarged terminations: **0063**

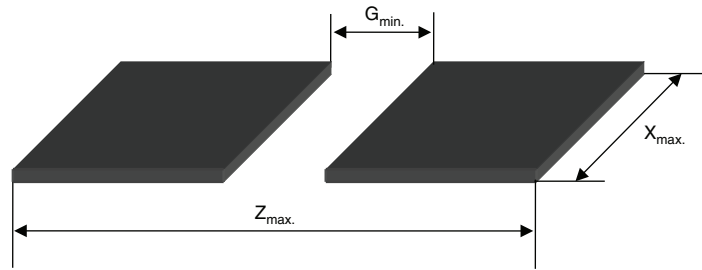
For stringent and special power dissipation requirements, the thermal resistance between the resistive layer and the solder joint can be reduced using enlarged terminations chip resistors which are soldered on large and thick copper pads acting as heat sinks (see application note: 53048 Power Dissipation in High Precision Vishay Sfernice Chip Resistors and Arrays (P Thin Film, PRA Arrays, CHP Thick Film) [www.vishay.com/doc?53048](http://www.vishay.com/doc?53048)).

Option to order: 0063 (applies to size 1206/1505/1020/2010/2512).

## DIMENSIONS (Option 0063) in millimeters



CASE SIZE	A	B	C	D	E
	± 0.152	± 0.127	± 0.127	± 0.127	± 0.127
1206	3.00	1.73	0.38	0.40	1.19
1505	3.70	1.25	0.50	0.50	1.54
2010	5.03	2.64	0.50	0.50	2.20
1020	2.49	5.18	0.50	0.31	0.93
2208	5.53	2.05	0.50	0.50	2.45
2512	6.30	3.30	0.50	0.50	2.84

**SUGGESTED LAND PATTERN (Option 0063)**


CASE SIZE	DIMENSIONS (IN MILLIMETERS)		
	$Z_{max.}$	$G_{min.}$	$X_{max.}$
1206	3.85	0.50	1.86
1505	4.55	0.50	1.38
2010	5.88	0.50	2.77
1020	3.34	0.50	5.31
2208	6.38	0.50	2.18
2512	7.15	0.50	3.43

**OPTION: MARKING**

Option to order 0013:

Marking of ohmic value and tolerance:

Sizes: 0805 to 1005: 3 digits marking (according to EIA-96)

Sizes: 1206 to 2010: 4 digits marking (same codification than in the ordering procedure)

Tolerance indicated by a color dot.

Option to order 0014:

Marking of ohmic value:

Sizes 0805 to 1005: 3 digits marking (according to EIA-96)

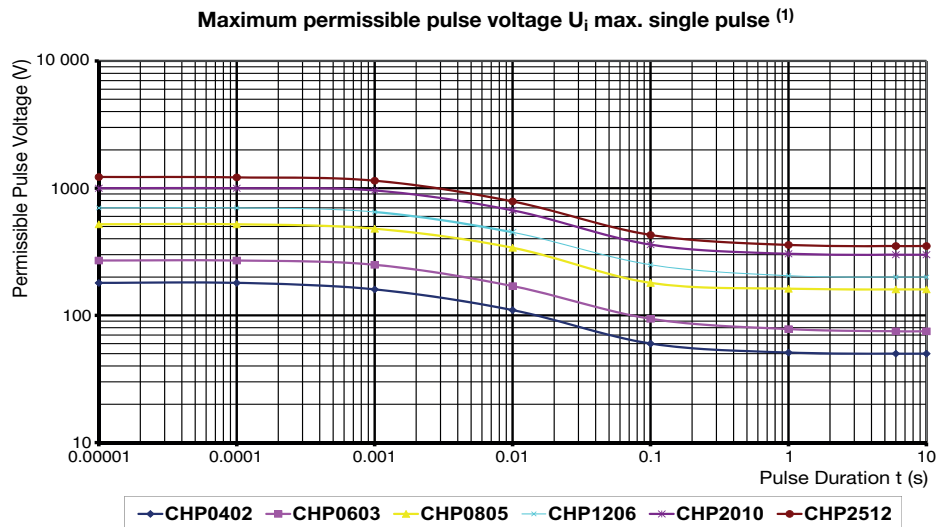
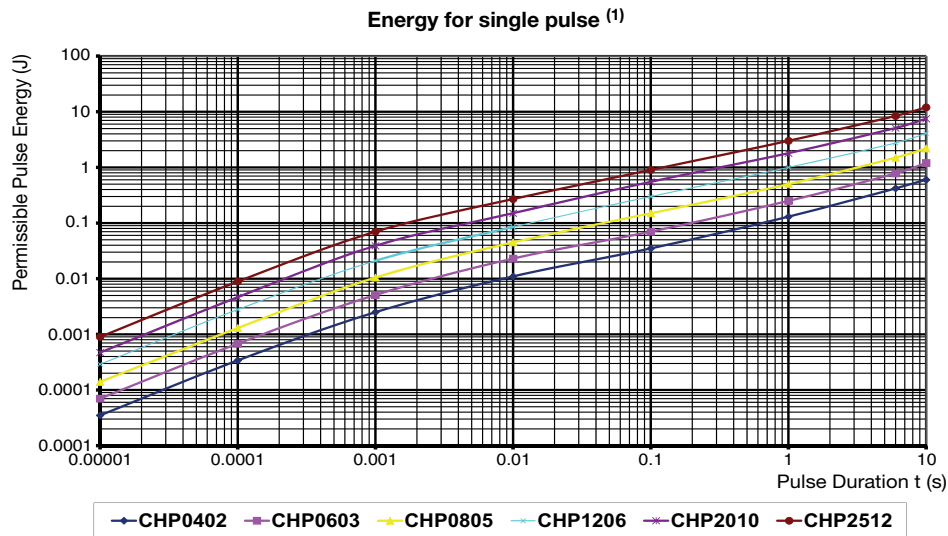
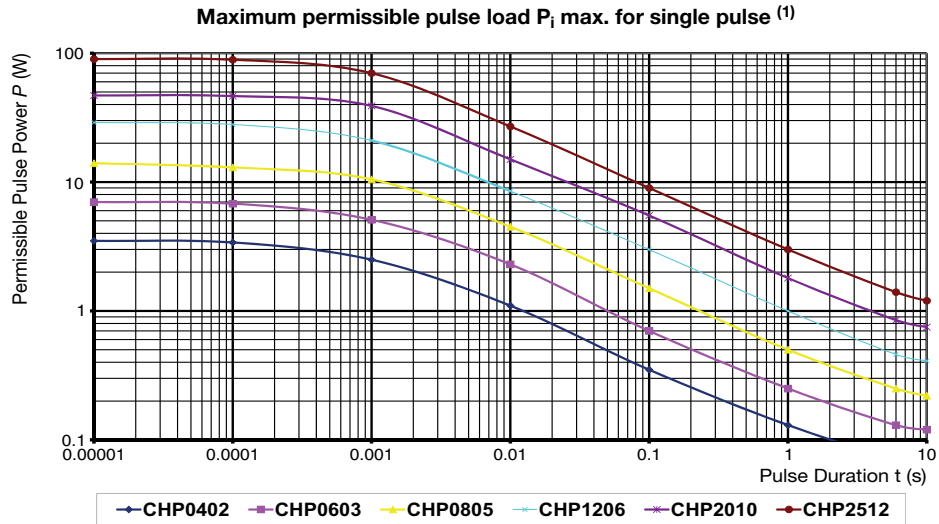
Sizes 1206 to 2010: 4 digits marking (same codification than in the ordering procedure)

No standard marking available for smaller sizes.

A price adder will apply to the unit price of the parts for options 0013 and 0014.

**PERFORMANCE**

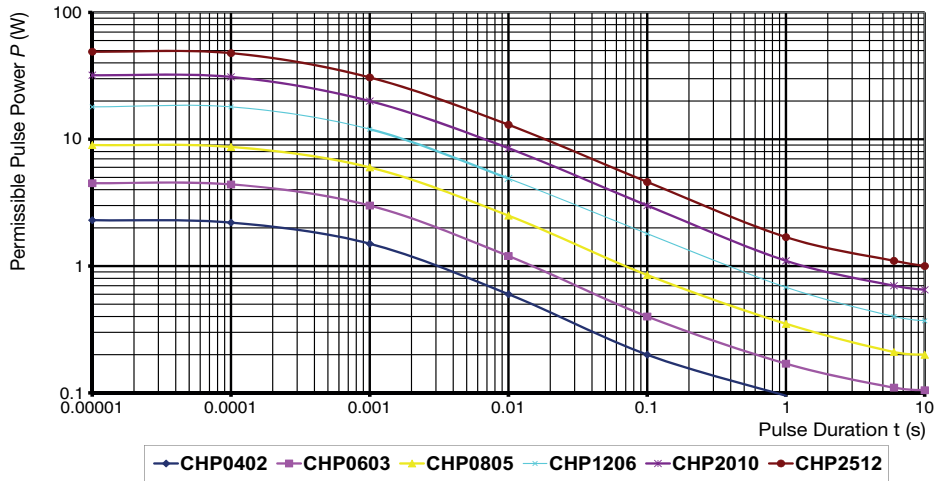
TESTS	CONDITIONS	REQUIREMENTS	TYPICAL VALUES AND DRIFTS
Termination adhesion	5N for 10 s	$\pm (0.25 \% + 0.05 \Omega)$	$< \pm 0.1 \%$
Resistance to solder heat	Immersion 10 s in Sn/Pb 60/40 at + 260 °C	$\pm (0.25 \% + 0.05 \Omega)$	$< \pm 0.1 \%$
Rapid temperature change	5 cycles - 55 °C      + 155 °C	$\pm (0.25 \% + 0.05 \Omega)$	$< \pm 0.1 \%$
Climatic sequence	Phase A dry heat Phase B damp heat Phase C cold - 55 °C Phase D damp heat 5 cycles	$\pm (1 \% + 0.05 \Omega)$	$< \pm 0.2 \%$
Humidity (steady state)	56 days	$\pm (1 \% + 0.05 \Omega)$	$< \pm 0.2 \%$
Moisture resistance	AEC-Q200 85 °C/85 % RH/Pn/10 1000 h	5 % + 0.05 $\Omega$	Max. < 3 % + 0.05 $\Omega$
Short time overload	6.25 Pr for 2 s	$\pm (0.25 \% + 0.05 \Omega)$	$< \pm 0.1 \%$
Load life	1000 h at rated power 90°/30' at + 70 °C	1000 h $\pm (1 \% + 0.05 \Omega)$	1000 h    2000 h    10 000 h < 0.25 %    < 0.5 %    < 1 %



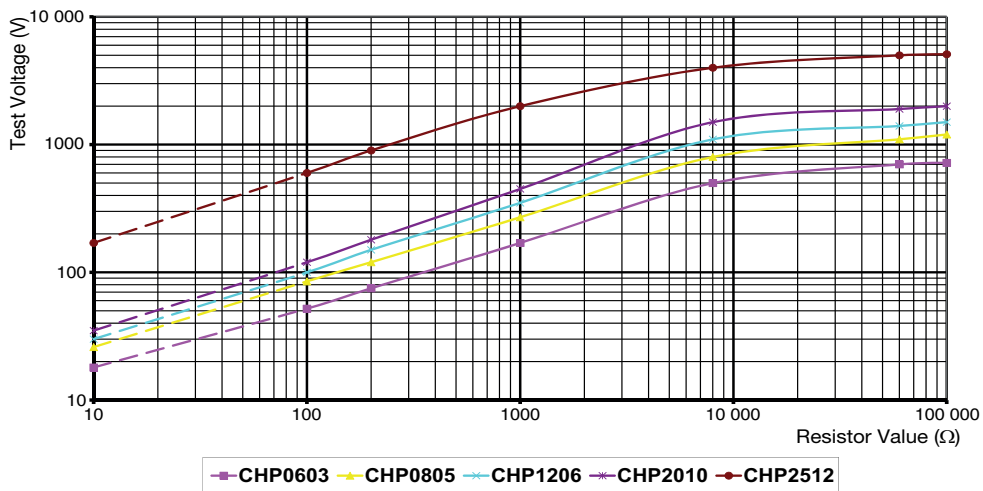
**Note**

<sup>(1)</sup> One should use the 3 curves together to get the right performances.

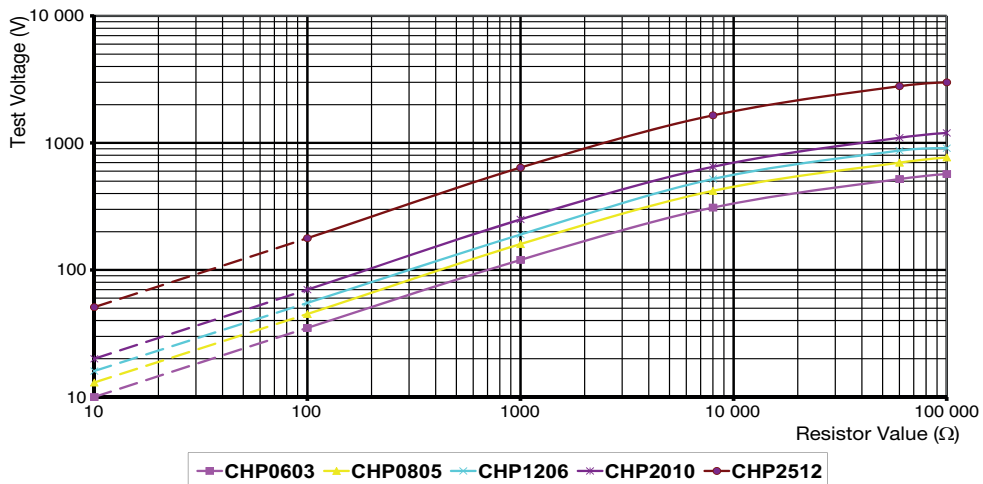
Maximum permissible pulse load  $P_i$  max.



1.2/50  $\mu$ s lightning surge



10/700  $\mu$ s lightning surge





GLOBAL PART NUMBER INFORMATION																		
LIMITED TO 18 DIGITS: If more digits are necessary a cofication of some digits might be necessary																		
C	H	P		0	8	0	5	K	1	0	0	1	F	B	T	9	9	9
GLOBAL MODEL	SIZE	TCR	VALUE	TOLERANCE	TERMINATION	PACKAGING (1)	OPTION											
CHP HCHP (3 or 4 digits)	0502 0505 0603 0805 1005 1206 1505 2010 1020 1010 2208 2512	K = 100 ppm L = 200 ppm	The first 3 digits are significant figures and the last digit specifies the number of zeros to follow. R designates decimal point  10R0 = 10 Ω 3901 = 3900 Ω 1004 = 1 MΩ	D = ± 0.5 % F = ± 1 % G = ± 2 % J = ± 5 %	B: SnPb over nickel barrier N: SnAg over nickel barrier F: SnAg over nickel barrier (one face) G: Gold over nickel barrier W: Gold over nickel barrier (one face)  B: Lead bearing version N and G: Lead (Pb)-free/ RoHS version	For more information see Codification of Packaging table	From 1 to 3 digits, leave blank if no option											
Historical Part Number examples: CHP2010K50R0FBT100 (tapes of 100 pieces) CHP0805K33R0FG0045 (CHP option 45) HCHP0805K16R5FBT55 (HCHP option 55) CHP2010L1006JN (waffle pack)																		

**Notes**

- Historical part numbers are not recommended but can still be used for ordering.
- (1) For paper tape please consult Vishay Sfernice.

CODIFICATION OF PACKAGING	
<b>WAFFLE PACK</b>	
W	10 min., 1 mult
WA	100 min., 100 mult (available only in size 1206)
<b>PLASTIC TAPE</b>	
T	100 min., 1 mult
TA	100 min., 100 mult
TB	250 min., 250 mult
TC	500 min., 500 mult
TD	1000 min., 1000 mult
TE	2500 min., 2500 mult
TF	Full tape (qunatity depending on size of chips)
<b>PAPER TAPE</b>	
PT	100 min., 1 mult
PA	100 min., 100 mult
PB	250 min., 250 mult
PC	500 min., 500 mult
PD	1000 min., 1000 mult
PE	2500 min., 2500 mult
PF	Full tape (qunatity depending on size of chips)

CODIFICATION OF OPTIONS ON TWO DIGITS			
OPTION	OPTION 2 DIGITS	OPTION	OPTION 2 DIGITS
..	..	0126	1A
0099	99	0127	1B
0100	0A	0128	1C
0101	0B	..	..
0102	0C	0320	8M
0103	0D	0321	8N
0104	0E	0322	8O
0105	0F	0323	8P
..	..	0324	8Q
0124	0Y	0325	8R
0125	0Z	..	..

CODIFICATION OF SIZES			
CODE 18	CODE 40	CODE 18	CODE 40
7	02016	M	22
8	0302	N	33
9	0402	O	44
A	0502	P	55
B	0505	Q	515
C	0603	R	48
D	0805	S	408
E	1005	T	816
F	1010	U	914
G	1020	V	073
H	1206	W	074
I	1505	X	100
J	2010	Y	135
K	2208	Z	182
L	2512		





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## Material Category Policy

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.**

**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.**



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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